

**FOR IMMEDIATE RELEASE**

## **Final Agreement Reached on the Sale of Hiroshima Elpida's 200mm Wafer Processing Equipment**

**TOKYO, JAPAN, April 10, 2007** –Elpida Memory, Inc. (Elpida), Japan's leading global supplier of Dynamic Random Access Memory (DRAM), together with its consolidated subsidiary Hiroshima Elpida Memory, Inc. (Hiroshima Elpida) entered into a basic agreement on February 19, 2007 regarding the transfer of fixed assets. Today we are announcing that the asset transfer price, schedule and details have been finalized.

\* \* \*

### **1. Asset transfer details**

Assets to be transferred:

Hiroshima Elpida's 200mm wafer processing equipment  
(total wafer processing capacity: approx. 50,000 wafers/month)

Location of assets:

7-10, Yoshikawa Kogyo Danchi, Higashi Hiroshima-shi, Hiroshima, Japan

Asset transfer price: US\$320 million

### **2. Asset transfer schedule**

Closing date: April 27, 2007

### **3. Future Issues**

An initial phase of delivery of wafer processing equipment (approximately half of the total capacity) will be completed by the end of November 2007. The remaining equipment will be delivered during the second phase which is scheduled to be completed in 2008.

Production at Hiroshima Elpida's 200mm facility will be continued, with adjustments to the volume of wafer production, until the delivery of the wafer processing equipment (the asset transfer) is complete.

Also, the asset transfer is expected to be recorded as a sale of fixed assets in the FY 2007 business year. The accounting treatment of this transaction, however, has yet to be determined. We plan to explain our eventual accounting decision at our scheduled April 24 business results announcement.

<Reference>

Recipient's corporate name: Cension Semiconductor Manufacturing Corporation (Chengdu)  
Recipient's address: No. 8 Kexin Road, Export Processing Zone (West Area),  
Chengdu, the People's Republic of China  
Recipient's official representative: Zheng Jin Yuan, President & CEO  
Description of recipient's business: Semiconductor Manufacturing  
Recipient's connection with Elpida: None

### **About Elpida Memory, Inc.**

Elpida Memory, Inc., (Tokyo Stock Exchange Code 6665), is a leading manufacturer of Dynamic Random Access Memory (DRAM) silicon chips. Our design, manufacturing, and sales operations are backed by our world class technology expertise. Our manufacturing facilities, Hiroshima Elpida Memory, Inc. (front-end processes) and Akita Elpida Memory, Inc. (back-end processes), utilize the most advanced manufacturing technologies available in the industry. Further, we have customer sales and marketing support offices in Japan, North America, Europe, Taiwan, Hong Kong and Singapore. Elpida's portfolio of advanced products features such characteristics as high-density, high-speed, low power and small packing profiles. We provide applications across a wide range of areas, including high-end servers, mobile phones and digital consumer electronics. For more information about Elpida, please visit <http://www.elpida.com>

*Information in this news release is current as of the timing of the release, but may be revised later without notice.*

### **Elpida Press Contacts:**

Tomoko Kobayashi  
Elpida Memory, Inc. (Japan)  
Tel: +81-3-3281-1648  
E-mail: [press@elpida.com](mailto:press@elpida.com)

-###-